L	Hits	Search Text	DB	Time stamp
Number				
1	0	(light-emitting-diode light-emitter) and	USPAT;	2004/09/25
		wafer-bond\$3 and solder	US-PGPUB;	10:27
			EPO; JPO;	
			IBM_TDB	†
2	0	, (,,,,,,,	USPAT;	2004/09/25
		wafer-bond\$3 with (intermetallic metal	US-PGPUB;	10:29
		metallic)	EPO; JPO;	
			IBM TDB	
3	3	(light-emitting-diode light-emitter	USPAT;	2004/09/25
		diode) and wafer-bond\$3 with	US-PGPUB;	11:18
		(intermetallic metal metallic)	EPO; JPO;	
			IBM TDB	
4	1	("5508718").PN.	USPAT;	2004/09/25
			US-PGPUB;	10:38
			EPO; JPO;	
			IBM_TDB	İ
5	1	("5008718").PN.	USPAT;	2004/09/25
			US-PGPUB;	10:43
			EPO; JPO;	
			IBM_TDB	
6	15	chen-shi-ming.in.	USPAT;	2004/09/25
		-	US-PGPUB;	10:43
			EPO; JPO;	
		,	IBM_TDB	
7	25	(light-emitting-diode light-emitter	USPAT;	2004/09/25
		diode) and (metal\$3 near3 eutectic near3	US-PGPUB;	11:20
		bond\$3) and transparen\$	EPO; JPO;	
			IBM TDB	